

**Données OMNIMATE - Prises RJ45
RJ45C6 R1V 3.2N4N TY**

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La gamme de produit comprend les conceptions suivantes :

- 90°, couché (horizontal) et 180°, debout (vertical)
- verrouillage / déverrouillage
- Systèmes de soudure THT, THR ou SMD
- Large gamme de formes, également avec des LED intégrées et des languettes de contact blindage
- Catégorie de puissance Cat. 3 à Cat. 6
- Version emballée sur plateau (TY) ou en rouleau (Tape-on-Reel, RL)

Propriétés et avantages :

- Plage de température étendue de -40 °C à +85 °C, pour une puissance maximale
- Couche d'or renforcée (30µ") pour une protection contre la corrosion améliorée
- une distance minimale de 3 mm garantit une soudure parfaite

Informations générales de commande

Type	RJ45C6 R1V 3.2N4N TY
Référence	2634590000
Version	Connecteur pour circuit imprimé, Prises RJ45, Raccordement soudé THT/THR, 180°, Nombre de pôles: 8
GTIN (EAN)	4050118651270
Cdt.	160 pièce(s)

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Caractéristiques techniques

Dimensions et poids

Poids net	7,475 g
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Conformité environnementale du produit

REACH SVHC	Lead 7439-92-1
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Caractéristiques du système

Angle de sortie	180°	Cycles d'enfichage	750
Degré de protection	IP20	Famille de produits	Données OMNIMATE - Prises RJ45
Montage sur le circuit imprimé	Raccordement soudé THT/THR	Nombre de pôles	8
Surface de blindage	nickelé		

Emballage

Longueur VPE	0,315 m	Largeur VPE	0,195 m
Hauteur VPE	0,065 m		

Classifications

ETIM 6.0	EC002637	eClass 6.2	27-26-07-04
eClass 9.0	27-44-04-02	eClass 9.1	27-44-04-02

Agréments

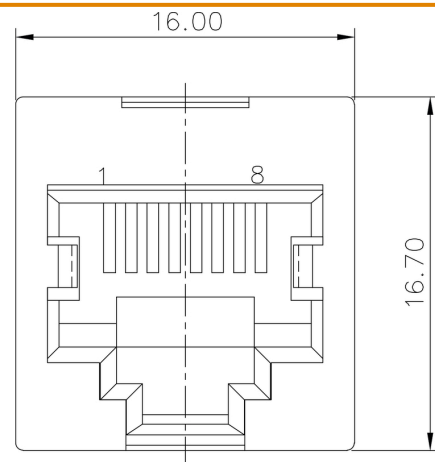
ROHS	Conforme
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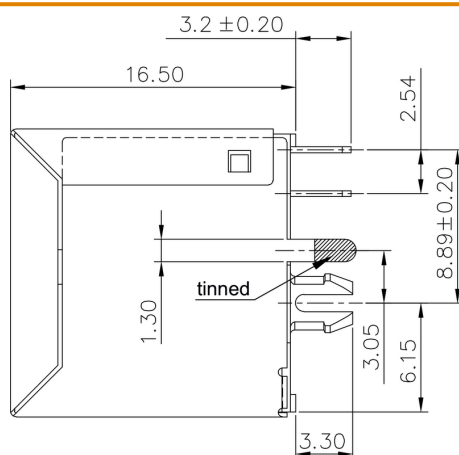
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Dessins

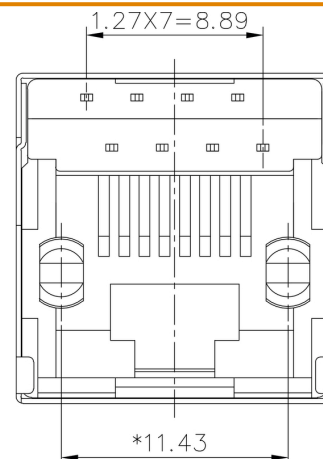
Dessin coté



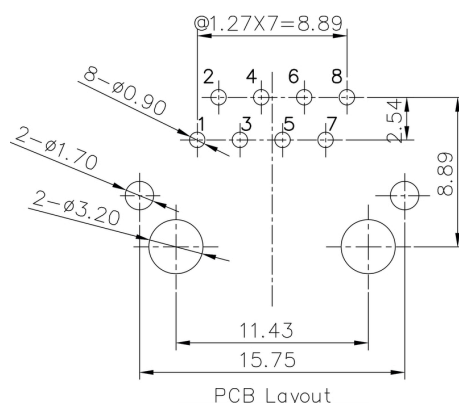
Dessin coté



Dessin coté



Conception de la plaque de circuit imprimé

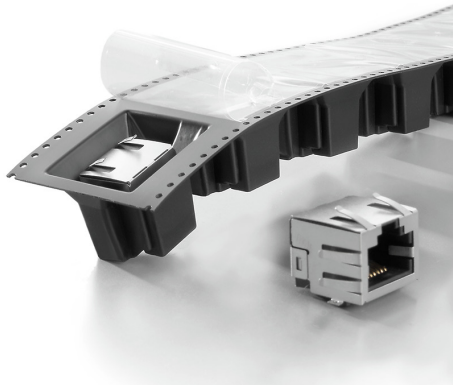


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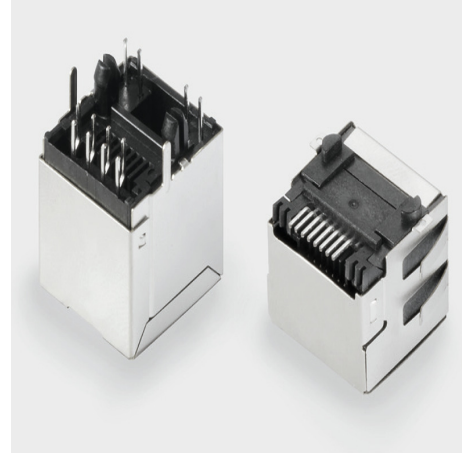
Avantages produit



Process-optimised packaging
Tape-on-reel or tray

Avantages produit

Avantages produit



Trouble-free assembly
Short, chamfered solder pins



Suitable for all soldering processes
SMT, THT or THR

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Dessins

Légende

RJ45	G1	R1	U1	U2	E4	GY/GY	TY
							Packaging TY LED Y/G G/Y GY/GY O/G R/O ... N Contact surface thickness 4 EMI tabs (ground fingers) E Solder Pin length 3.2 1.6 D Direction, latch style U D V Number of Ports 1 12; 14; ... 21; 41; ... Assembly on PCB R S T Performance Category C5 C6 C6A C5e M G1 G10 MP MP+ NP
							Ty Tray in box (manual assembly) Tape on Reel (automated assembly)
							Yellow/Green Green/Yellow (standard) Green-Yellow/Green-Yellow Orange-Green Red/Orange ... (further combinations possible) without LED
							1 = 3µ", 2 = 6µ", 3 = 15µ", 4 = 30µ", 5 = 50µ"
							E = with EMI tabs N = without EMI tabs
							3.2 mm 1.6 mm SMD
							Horizontal (90°, side entry), latch up Horizontal (90°, side entry), latch down Vertical (180°, top entry) Diagonal (45°), latch up
							1 Port multi ports side by side, Multiport multi ports about each other, Multilevel
							Through Hole Reflow - THR Soldering process: Wave or Reflow soldering Surface Mount Technology - SMT Soldering process: Reflow soldering Through Hole Technology - THT Soldering process: Wave
							Category 5 Category 6 Category 6A Category 5e 10/100 Mbit 10/100/1000 Mbit 10 Gbit Unshielded 10/100 Mbit with POE 10/100 Mbit with POE+

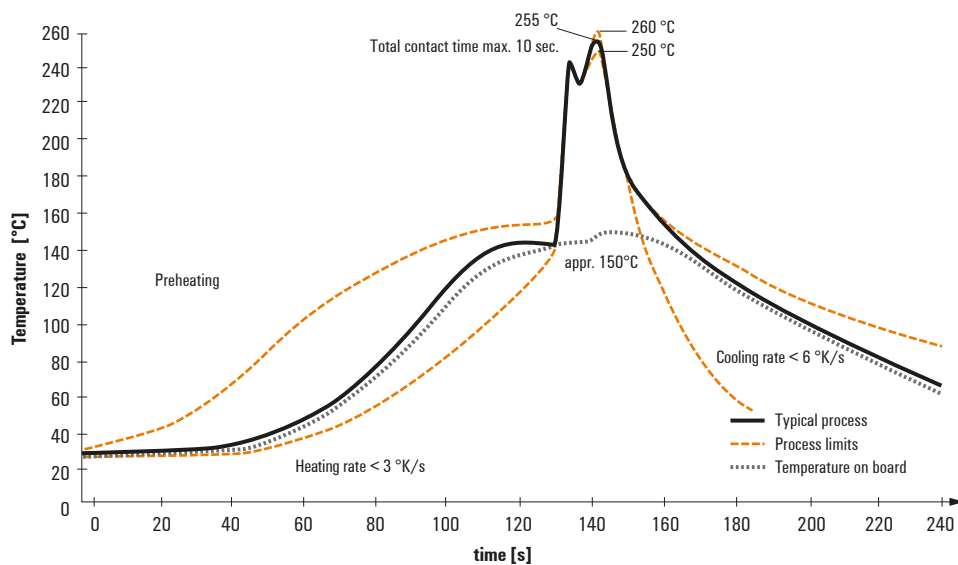
Recommended wave soldering profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.